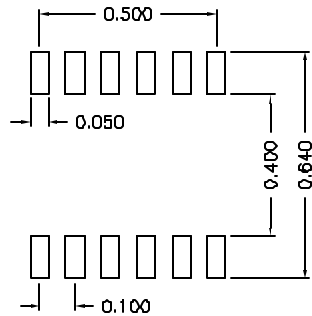
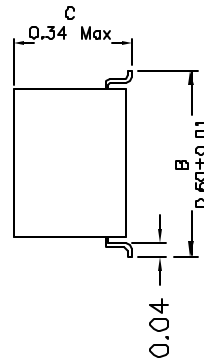
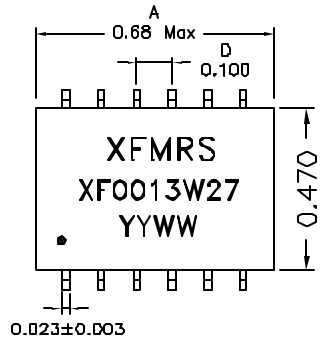
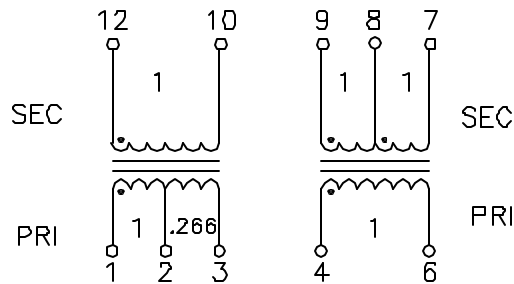


1. Dimensions:



SUGGESTED PAD LAYOUT

2. Schematic:



DOC. REV: A/2

3. Electrical Specifications: @25°C

- Isolation Voltage: 500 VAC Pri to Sec for 60 Sec
- Turns Ratio: (10-12:1-2:1-3)=1:1:1.266±5%
- Turns Ratio: (4-6:9-7)=1:2CT±5%
- OCL: P12-10 1.5mH Min @100KHz 0.2V
- OCL: P4-6 1.2mH Min @100KHz 0.2V
- LL: P12-10 0.4uH Max @100KHz 0.2V Short 1-3
- LL: P4-6 0.5uH Max @100KHz 0.2V Short 9-7
- Cw/w: P12-1 40pF Max @1MHz 0.5V
- Cw/w: P4-9 40pF Max @1MHz 0.5V
- DCR: P1-3 0.93 Ohms Max
- DCR: P9-7 1.24 Ohms Max
- DCR: P4-6, 12-10 0.70 Ohms Max

Notes:

1. Solderability: Leads shall meet MIL-STD-202C, Method 20BH for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity: ±0.004"(0.102mm)
9. Moisture Sensitivity: Level 3
10. Electrical and mechanical specifications 100% tested
11. RoHS Compliant Component

XFMRS Inc www.XFMRS.com		Title: SMD T1/E1 ISOLATION MODULE	
UNLESS OTHERWISE SPECIFIED		P/N: XF0013W27	REV. A
TOLERANCES: .xxx ±0.010		DWN. 李小锋	Nov-01-05
Dimensions in Inch		CHK. 廖玉坤	Nov-01-05
SHEET 1 OF 1		APP. BW	Nov-01-05